



Product End-of-Life Disassembly Instructions

Product Category: Networking Equipment

Marketing Name / Model

[List multiple models if applicable.]

HP A5900AF-48XG-4QSFP-SWITCH (JC772A)

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	6
Batteries	All types including standard alkaline and lithium coin or button style batteries	0
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords		2
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		4
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Screw driver	2#

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove slide 1 from the chassis
2. Unscrew the screws on metal part 2, and then remove metal part 2 from the chassis.
3. Unscrew all screws on mounting angle 3, and then remove the mounting angle 3.
4. Unscrew all screws on top cover 4, and then remove top cover 4.
5. Unscrew all screws on front cover 5 , and then remove front cover 5.
6. Remove all of the inner cables.
7. Unscrew all screws of battery 6, and then remove battery 6 from the chassis.
8. Unscrew all screws on fan 7, and then remove fan 7 from the chassis.
9. Unscrew all screws on bracket 8, and then remove bracket 8 and PCB 11 from base 12.
10. Unscrew all screws on PCB 9, and then remove PCB 9 from the chassis.
11. Unscrew all screws on PCB 10, and then remove PCB 10 from the chassis.
12. Unscrew all screws on PCB 7-2, and then remove PCB 7-2 from fan 7-1.
13. Unscrew all screws on fan rack 7-3, and then remove fan rack 7-3 from fan 7-1.
14. Unscrew all screws on fan 7-4, and then remove fan 7-4 from fan rack 7-3.
15. Unscrew all screws on radiator 11-2, and then remove radiator 11-2 from PCB 11-1.
16. Remove all of the labels from the chassis.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

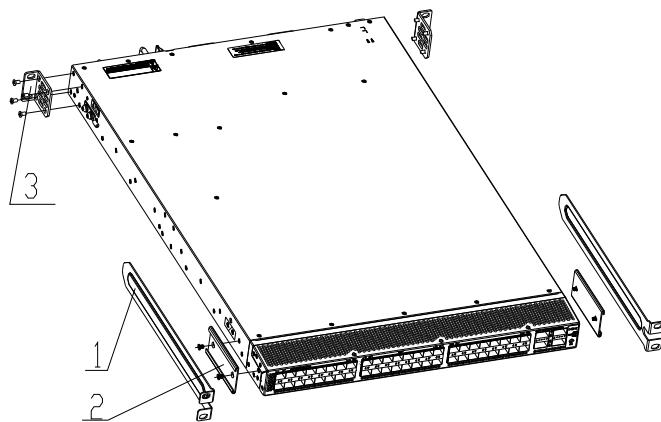


Figure1 Remove slide 1 and mounting angle 3

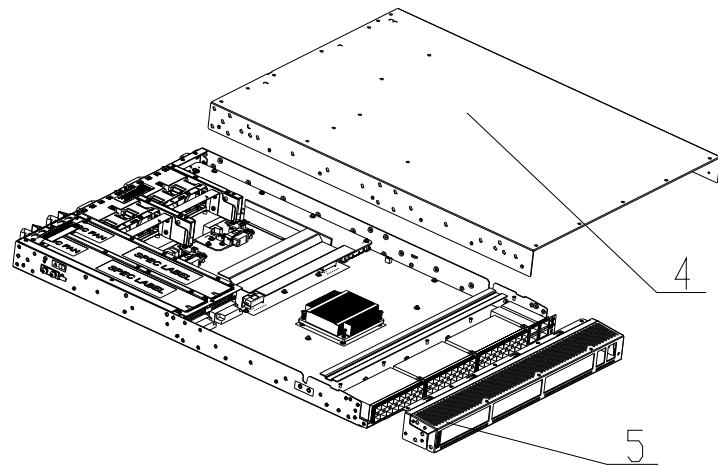


Figure2 Remove top cover 4 and front cover 5

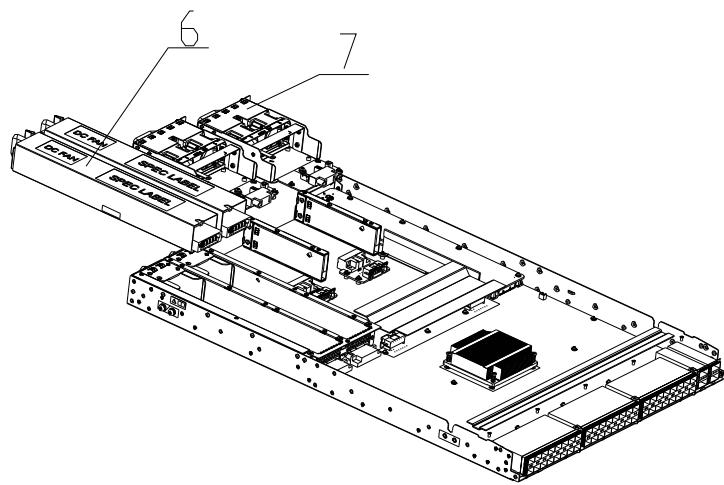


Figure3 Remove battery 6 and fan 7

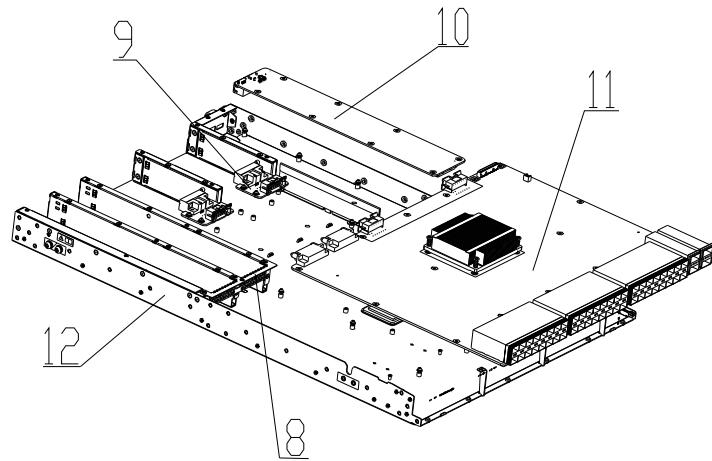


Figure4 Remove the PCBs

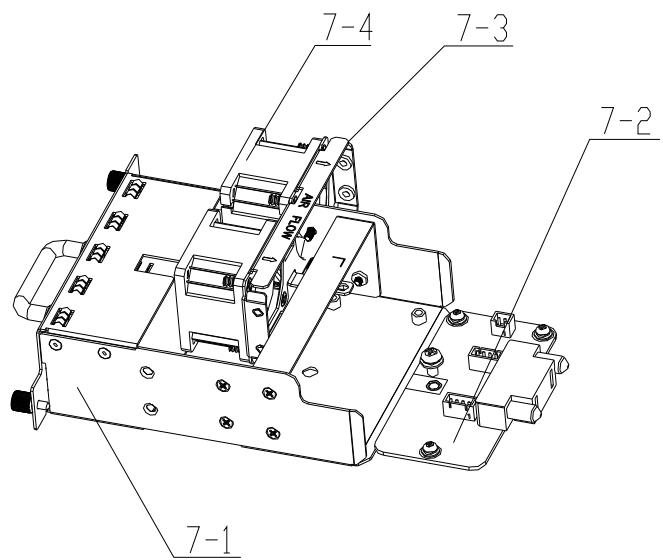


Figure5 Treatments to fan 7

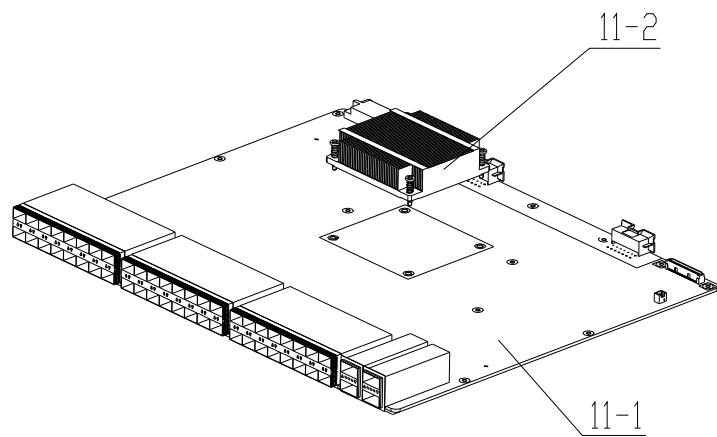


Figure6 Treatments to PCB 11